

Session Title:	[MB2] Novel CMP Slurries
Session Date:	November 14 (Mon.), 2022
Session Time:	15:00-16:50
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Dr. Youngsoo Park (Soulbrain, Korea)

[MB2-1] [Invited] 15:00-15:20

Oxide Polishing Mechanism of Nanoceria

Satoyuki Nomura (Showa Denko Materials Co., Ltd., Japan)

[MB2-2] [Invited] 15:20-15:50

Surface Transformation of Spin-On-Carbon Film via Forming Carbon Iron Complex for Remarkably Enhanced Polishing Rate

Jea-Gun Park, Jun-Myeong Lee, Seong-In Kim, Jong-Chan Lee (Hanyang Univ., Korea), and Jin-Hyung Park (UB Materials Inc., Korea)

[MB2-3] 15:50-16:10

Highly Dispersed Fe-Substituted Colloidal Silica Nanoparticles in Acidic pH Region for Tungsten Chemical Mechanical Planarization

Ganggyu Lee, Sungmin Kim, Hojin Jeong, Donghwan Kim, Myungju Woo, Yeram Lee, Taeseup Song, and Ungyu Paik (Hanyang Univ., Korea)

[MB2-4] 16:10-16:30

Strategic Approaches to Reduce Defects of CMP Processes

Jae-Dong Lee (KCTech, Korea)

[MB2-5] 16:30-16:50

Scavenger with Protonated Phosphite Ion for Incredible Nanoscale ZrO₂-Abrasive Dispersant Stability Enhancement and Related Tungsten-Film Surface Chemical-Mechanical Planarization

Seong-In Kim, Seon-Hwa Kang, Jin-Woong Cho, Ho-Jun Ahn, and Jea-Gun Park (Hanyang Univ., Korea)